

*IN THE UNITED STATES PATENT AND TRADEMARK OFFICE*

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In re Patent Application of:  
Shouhei KOZAKAI et al.

Application No.: 10/829,150

Confirmation No.: 5728

Filed: April 22, 2004

Art Unit: 1771

For: DICING/DIE BONDING ADHESION TAPE

Examiner: D. R. ZIRKER

**AMENDMENT IN RESPONSE TO NON-FINAL OFFICE ACTION**

MS Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

**INTRODUCTORY COMMENTS**

In response to the Office Action dated July 13, 2006, please amend the above-identified U.S. patent application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 4 of this paper.